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ABSTRACT

A MODULE HAVING INTEGRATED CIRCUITS

The invention relates to a data carrier having an integrated circuit and to a method for making the same. During production a carrier element equipped with an integrated circuit and contact surfaces is inserted in a recess in the data carrier blank. To be fixed in the recess the carrier element is underlaid with a melt adhesive film. To protect the integrated circuit from mechanical stresses a film strip made of material with high elastic deformability is additionally provided between the circuit and melt adhesive film.

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